

*5000*  
*#31a*  
*3-25-03*

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Charles W.C. Lin

Title: SUPPORT CIRCUIT WITH A TAPERED THROUGH-HOLE  
FOR A SEMICONDUCTOR CHIP ASSEMBLY

Serial No.: Unknown Filed: Herewith

Examiner: Unknown Group Art Unit: Unknown

Atty. Docket No.: P012-1

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ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

**PRELIMINARY AMENDMENT**

Dear Sir:

Please amend the application as follows.

**In the Title**

Replace the Title with SUPPORT CIRCUIT WITH A TAPERED THROUGH-HOLE  
FOR A SEMICONDUCTOR CHIP ASSEMBLY

**In the Specification**

Insert the following heading and paragraph at page 1, line 1:

**CROSS-REFERENCE TO RELATED APPLICATIONS**

*Q* This application is divisional of U.S. Application Serial No. 09/665,931 filed on  
September 20, 2000.

*Replace the paragraph at page 6, lines 13-32 with the following paragraph:*